



REVISION HISTORY

<u>Revision</u>	<u>Description</u>	<u>Issue Date</u>
Rev. 1.0	Initial Issue	Mar.15.2024
Rev. 1.1	1.Revised FEATURES :Low power consumption:Operating current : 15/12/10mA →10/9/8mA (TYP.) in page1 2.Revised PRODUCT FAMILY :Operating(I _{cc} ,TYP.):15/12/10mA →10/9/8mA in page1 3.Revised DC ELECTRICAL CHARACTERISTICS : Average Operating Power supply Current: I _{cc} <u>TYP.</u> *4 15/12/10→10/9/8 , <u>MAX.</u> :25/20/18→17/16/15 in page4 .	May.14.2025

FEATURES

- Fast access time : 45/55/70ns
- Low power consumption:
Operating current : 10/9/8mA (TYP.)
Standby current : 1.5μA (TYP.)
- Single 2.7V ~ 5.5V power supply
- All outputs TTL compatible
- Fully static operation
- Tri-state output
- Data byte control : LB# (DQ0 ~ DQ7)
UB# (DQ8 ~ DQ15)
- Data retention voltage : 1.5V (MIN.)
- **Green package available**
- Package : 44-pin 400 mil TSOP II
48-ball 6mm x 8mm TFBGA

GENERAL DESCRIPTION

The LY62W6416B is a 1,048,576-bit low power CMOS static random access memory organized as 65,536 words by 16 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

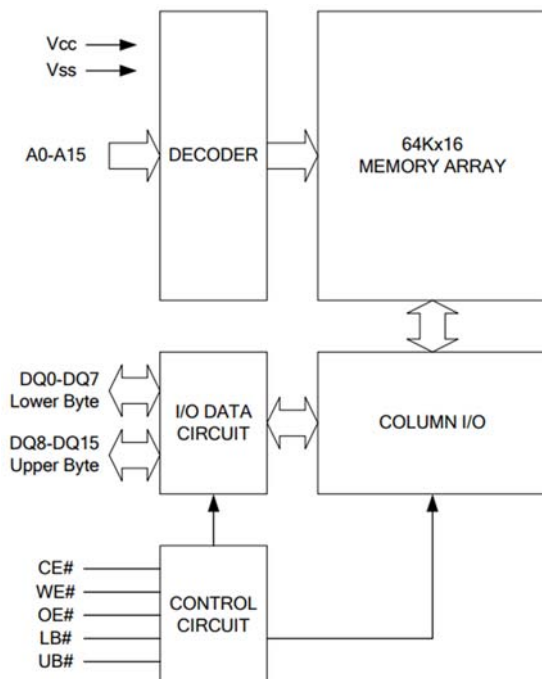
The LY62W6416B is well designed for low power application, and particularly well suited for battery back-up nonvolatile memory application.

The LY62W6416B operates from a single power supply of 2.7V ~ 5.5V and all outputs are fully TTL compatible.

PRODUCT FAMILY

Product Family	Operating Temperature	V _{CC} Range	Speed	Power Dissipation	
				Standby(I _{SB1} ,TYP.)	Operating(I _{CC} ,TYP.)
LY62W6416B	0 ~ 70°C	2.7 ~ 5.5V	45/55/70ns	1.5μA	10/9/8mA
LY62W6416B(I)	-40 ~ 85°C	2.7 ~ 5.5V	45/55/70ns	1.5μA	10/9/8mA

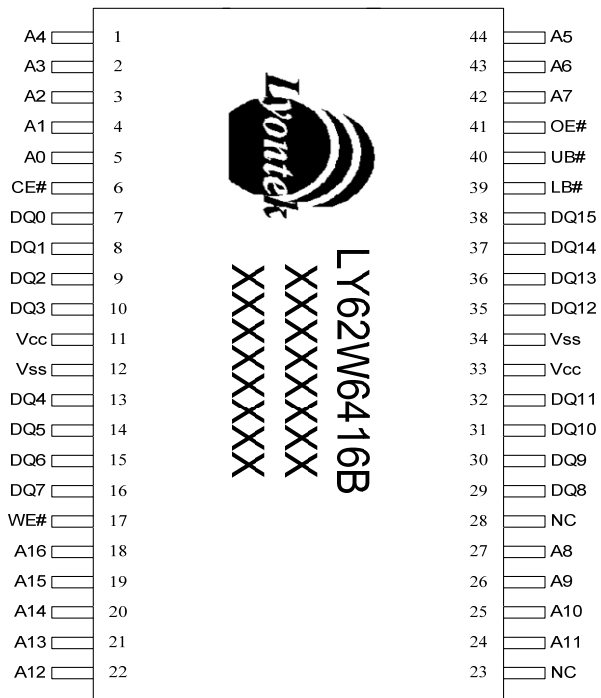
FUNCTIONAL BLOCK DIAGRAM



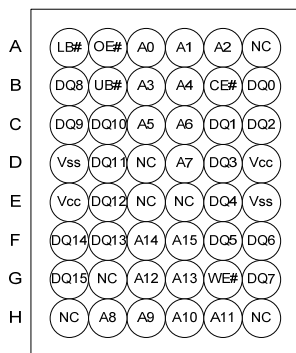
PIN DESCRIPTION

SYMBOL	DESCRIPTION
A0 - A15	Address Inputs
DQ0 - DQ15	Data Inputs/Outputs
CE#	Chip Enable Input
WE#	Write Enable Input
OE#	Output Enable Input
LB#	Lower Byte Control
UB#	Upper Byte Control
V _{CC}	Power Supply
V _{SS}	Ground
NC	No Connection

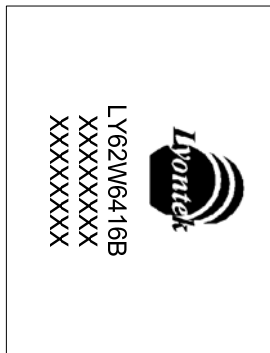
PIN CONFIGURATION



TSOP II



TFBGA(See through with Top View)





ABSOLUTE MAXIMUM RATINGS*

PARAMETER	SYMBOL	RATING	UNIT
Voltage on V_{CC} relative to V_{SS}	V_{T1}	-0.5 to 6.5	V
Voltage on any other pin relative to V_{SS}	V_{T2}	-0.5 to $V_{CC}+0.5$	V
Operating Temperature	T_A	0 to 70(C grade)	°C
		-40 to 85(I grade)	
Storage Temperature	T_{STG}	-65 to 150	°C
Power Dissipation	P_D	1	W
DC Output Current	I_{OUT}	50	mA

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

TRUTH TABLE

MODE	CE#	OE#	WE#	LB#	UB#	I/O OPERATION		SUPPLY CURRENT
						DQ0 - DQ7	DQ8 - DQ15	
Standby	H	X	X	X	X	High-Z	High-Z	I_{SB1}
	X	X	X	H	H	High-Z	High-Z	
Output Disable	L	H	H	L	X	High-Z	High-Z	I_{CC}, I_{CC1}
	L	H	H	X	L	High-Z	High-Z	
Read	L	L	H	L	H	D_{OUT}	High-Z	I_{CC}, I_{CC1}
	L	L	H	H	L	High-Z	D_{OUT}	
	L	L	H	L	L	D_{OUT}	D_{OUT}	
Write	L	X	L	L	H	D_{IN}	High-Z	I_{CC}, I_{CC1}
	L	X	L	H	L	High-Z	D_{IN}	
	L	X	L	L	L	D_{IN}	D_{IN}	

Note: H = V_{IH} , L = V_{IL} , X = Don't care.



DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP. ^{*4}	MAX.	UNIT
Supply Voltage	V_{CC}		2.7	3.0	5.5	V
Input High Voltage	V_{IH}^{*1}		$0.7 \cdot V_{CC}$	-	$V_{CC} + 0.3$	V
Input Low Voltage	V_{IL}^{*2}		- 0.2	-	0.6	V
Input Leakage Current	I_{LI}	$V_{CC} \geq V_{IN} \geq V_{SS}$	- 1	-	1	μA
Output Leakage Current	I_{LO}	$V_{CC} \geq V_{OUT} \geq V_{SS}$, Output Disabled	- 1	-	1	μA
Output High Voltage	V_{OH}	$I_{OH} = -1mA$	2.4	2.7	-	V
Output Low Voltage	V_{OL}	$I_{OL} = 2mA$	-	-	0.4	V
Average Operating Power supply Current	I_{CC}	Cycle time = Min. $CE\# \leq 0.2V$, $I_{I/O} = 0mA$ Other pins at 0.2V or $V_{CC}-0.2V$	- 45	10	17	mA
			- 55	9	16	mA
			- 70	8	15	mA
	I_{CC1}	Cycle time = 1 μs $CE\# \leq 0.2V$, $I_{I/O} = 0mA$ Other pins at 0.2V or $V_{CC}-0.2V$	-	2	4	mA
Standby Power Supply Current	I_{SB1}	$CE\# \geq V_{CC}-0.2V$ Other pins at 0.2V or $V_{CC}-0.2V$	SL^{*5} 25°C	1.2	3.2	μA
			SLI^{*5} 40°C	1.5	3.5	μA
			SL	1.5	10	μA
			SLI	1.5	15	μA

Notes:

1. $V_{IH}(\max) = V_{CC} + 3.0V$ for pulse width less than 10ns.
2. $V_{IL}(\min) = V_{SS} - 3.0V$ for pulse width less than 10ns.
3. Over/Undershoot specifications are characterized, not 100% tested.
4. Typical values are included for reference only and are not guaranteed or tested.
Typical values are measured at $V_{CC} = V_{CC}(\text{TYP.})$ and $T_A = 25^\circ C$
5. This parameter is measured at $V_{CC} = 3.0V$

CAPACITANCE ($T_A = 25^\circ C$, $f = 1.0MHz$)

PARAMETER	SYMBOL	MIN.	MAX.	UNIT
Input Capacitance	C_{IN}	-	6	pF
Input/Output Capacitance	$C_{I/O}$	-	8	pF

Note : These parameters are guaranteed by device characterization, but not production tested.

AC TEST CONDITIONS

Input Pulse Levels	0.2V to $V_{CC} - 0.2V$
Input Rise and Fall Times	3ns
Input and Output Timing Reference Levels	1.5V
Output Load	$C_L = 30pF + 1TTL$, $I_{OH}/I_{OL} = -2mA/4mA$



AC ELECTRICAL CHARACTERISTICS

(1) READ CYCLE

PARAMETER	SYM.	LY62W6416B-45		LY62W6416B-55		LY62W6416B-70		UNIT
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Read Cycle Time	t _{RC}	45	-	55	-	70	-	ns
Address Access Time	t _{AA}	-	45	-	55	-	70	ns
Chip Enable Access Time	t _{ACE}	-	45	-	55	-	70	ns
Output Enable Access Time	t _{OE}	-	25	-	30	-	35	ns
Chip Enable to Output in Low-Z	t _{CLZ} *	10	-	10	-	10	-	ns
Output Enable to Output in Low-Z	t _{OLZ} *	5	-	5	-	5	-	ns
Chip Disable to Output in High-Z	t _{CHZ} *	-	20	-	20	-	25	ns
Output Disable to Output in High-Z	t _{OHZ} *	-	20	-	20	-	25	ns
Output Hold from Address Change	t _{OH}	10	-	10	-	10	-	ns
LB#, UB# Access Time	t _{BA}	-	45	-	55	-	70	ns
LB#, UB# to High-Z Output	t _{BHZ} *	-	20	-	25	-	30	ns
LB#, UB# to Low-Z Output	t _{BLZ} *	10	-	10	-	10	-	ns

(2) WRITE CYCLE

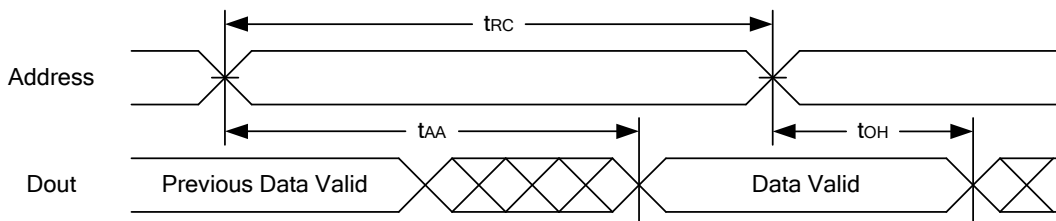
PARAMETER	SYM.	LY62W6416B-45		LY62W6416B-55		LY62W6416B-70		UNIT
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Write Cycle Time	t _{WC}	45	-	55	-	70	-	ns
Address Valid to End of Write	t _{AW}	40	-	50	-	60	-	ns
Chip Enable to End of Write	t _{CW}	40	-	50	-	60	-	ns
Address Set-up Time	t _{AS}	0	-	0	-	0	-	ns
Write Pulse Width	t _{WP}	35	-	45	-	55	-	ns
Write Recovery Time	t _{WR}	0	-	0	-	0	-	ns
Data to Write Time Overlap	t _{DW}	20	-	25	-	30	-	ns
Data Hold from End of Write Time	t _{DH}	0	-	0	-	0	-	ns
Output Active from End of Write	t _{OW} *	5	-	5	-	5	-	ns
Write to Output in High-Z	t _{WHZ} *	-	20	-	20	-	25	ns
LB#, UB# Valid to End of Write	t _{BW}	40	-	50	-	60	-	ns

*These parameters are guaranteed by device characterization, but not production tested.

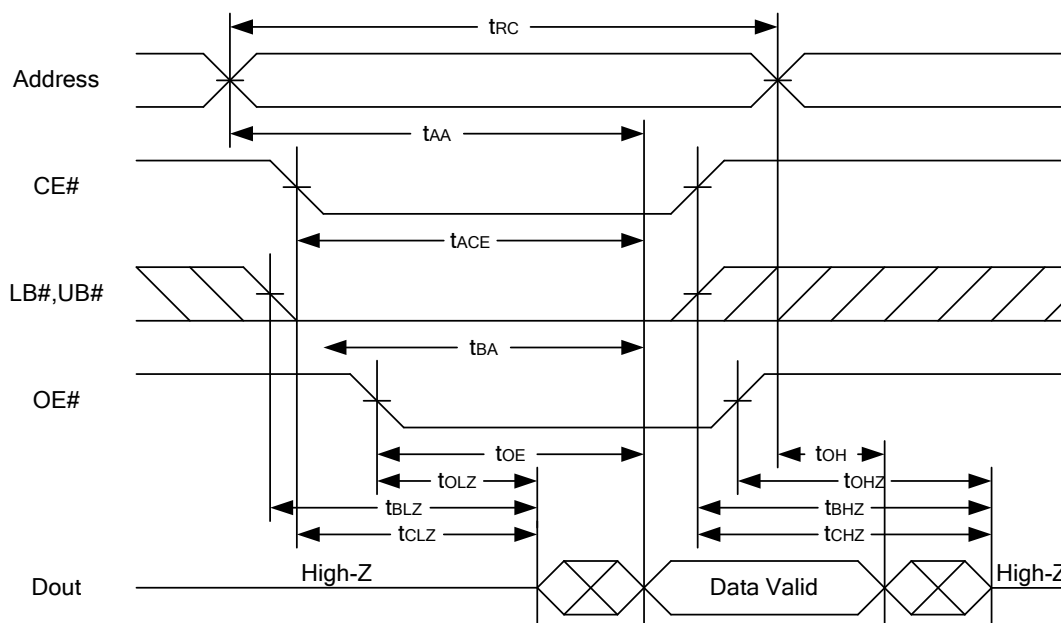


TIMING WAVEFORMS

READ CYCLE 1 (Address Controlled) (1,2)



READ CYCLE 2 (CE# and OE# Controlled) (1,3,4,5)

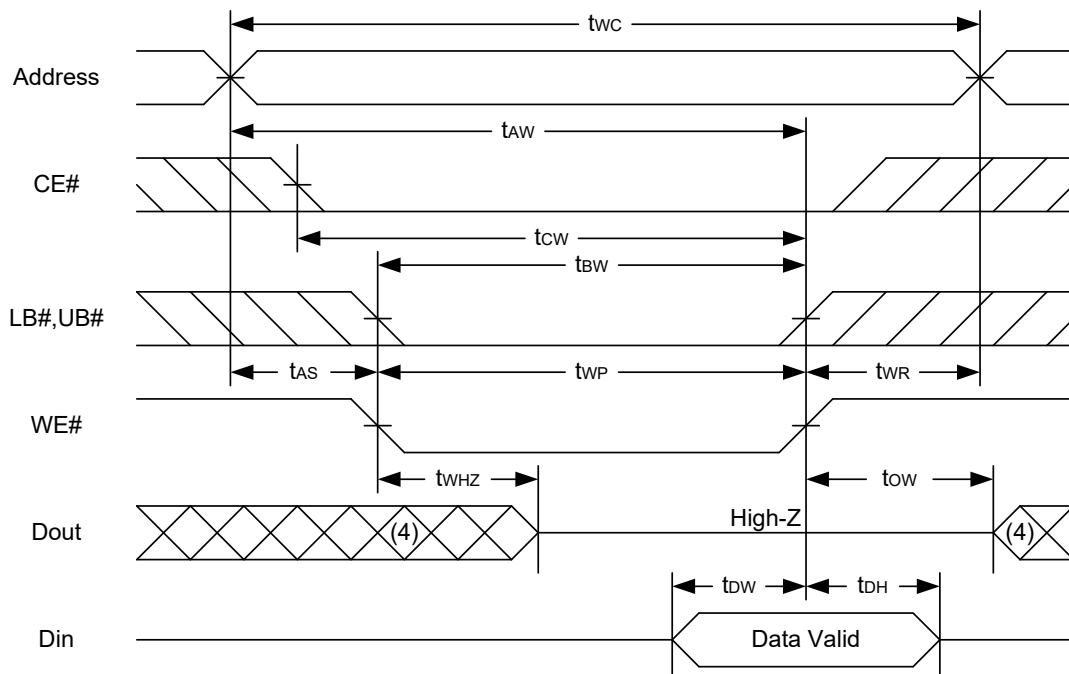


Notes :

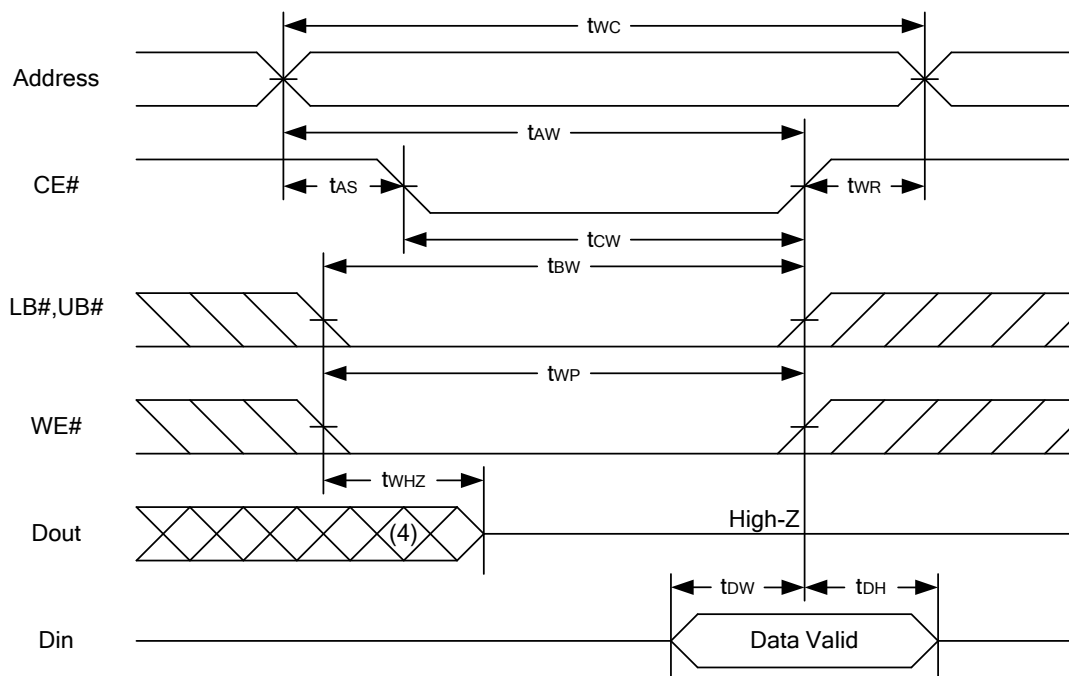
1. WE# is high for read cycle.
2. Device is continuously selected OE# = low, CE# = low, LB# or UB# = low.
3. Address must be valid prior to or coincident with CE# = low, LB# or UB# = low transition; otherwise tAA is the limiting parameter.
4. tCLZ, tBLZ, tOLZ, tCHZ, tBHZ and tOHZ are specified with CL = 5pF. Transition is measured $\pm 500\text{mV}$ from steady state.
5. At any given temperature and voltage condition, tCHZ is less than tCLZ, tBHZ is less than tBLZ, tOHZ is less than tOLZ.



WRITE CYCLE 1 (WE# Controlled) (1,2,4,5)

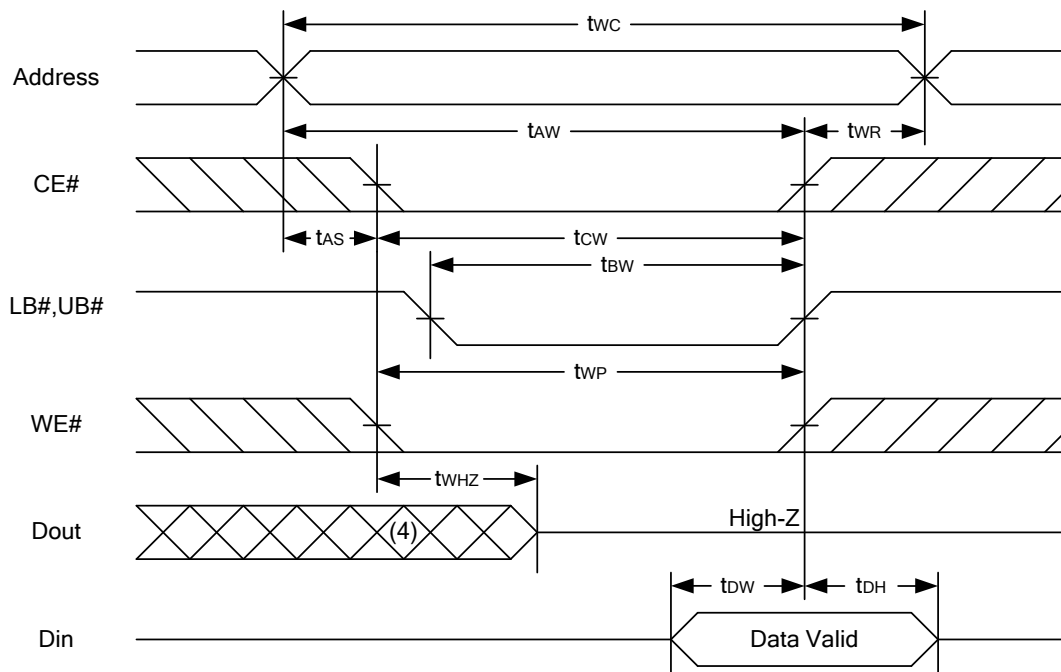


WRITE CYCLE 2 (CE# Controlled) (1,4,5)





WRITE CYCLE 3 (LB#,UB# Controlled) (1,4,5)



Notes :

- 1.A write occurs during the overlap of a low CE#, low WE#, LB# or UB# = low.
- 2.During a WE# controlled write cycle with OE# low, t_{WP} must be greater than $t_{WHZ} + t_{DW}$ to allow the drivers to turn off and data to be placed on the bus.
- 3.During this period, I/O pins are in the output state, and input signals must not be applied.
- 4.If the CE#, LB#, UB# low transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
5. t_{OW} and t_{WHZ} are specified with $C_L = 5\text{pF}$. Transition is measured $\pm 500\text{mV}$ from steady state.

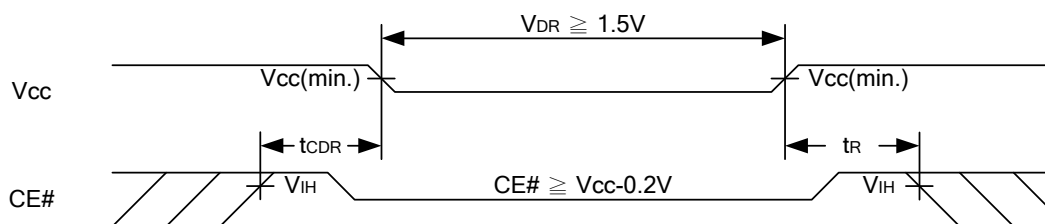
DATA RETENTION CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V _{CC} for Data Retention	V _{DR}	CE# $\geq$ V _{CC} -0.2V	1.5	-	5.5	V
Data Retention Current	I _{DR}	V _{CC} = 1.5V CE# $\geq$ V _{CC} -0.2V Other pins at 0.2V or V _{CC} -0.2V	SL 25°C	-	1.2	μ A
			SLI 40°C	-	1.5	μ A
			SL	-	1.5	μ A
			SLI	-	1.5	μ A
Chip Disable to Data Retention Time	t _{CDR}	See Data Retention Waveforms (below)	0	-	-	ns
Recovery Time	t _R		t _{RC} *	-	-	ns

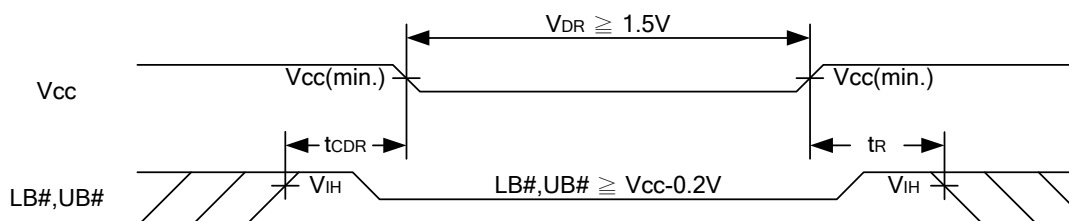
t_{RC}* = Read Cycle Time

DATA RETENTION WAVEFORM

Low V_{CC} Data Retention Waveform (1) (CE# controlled)



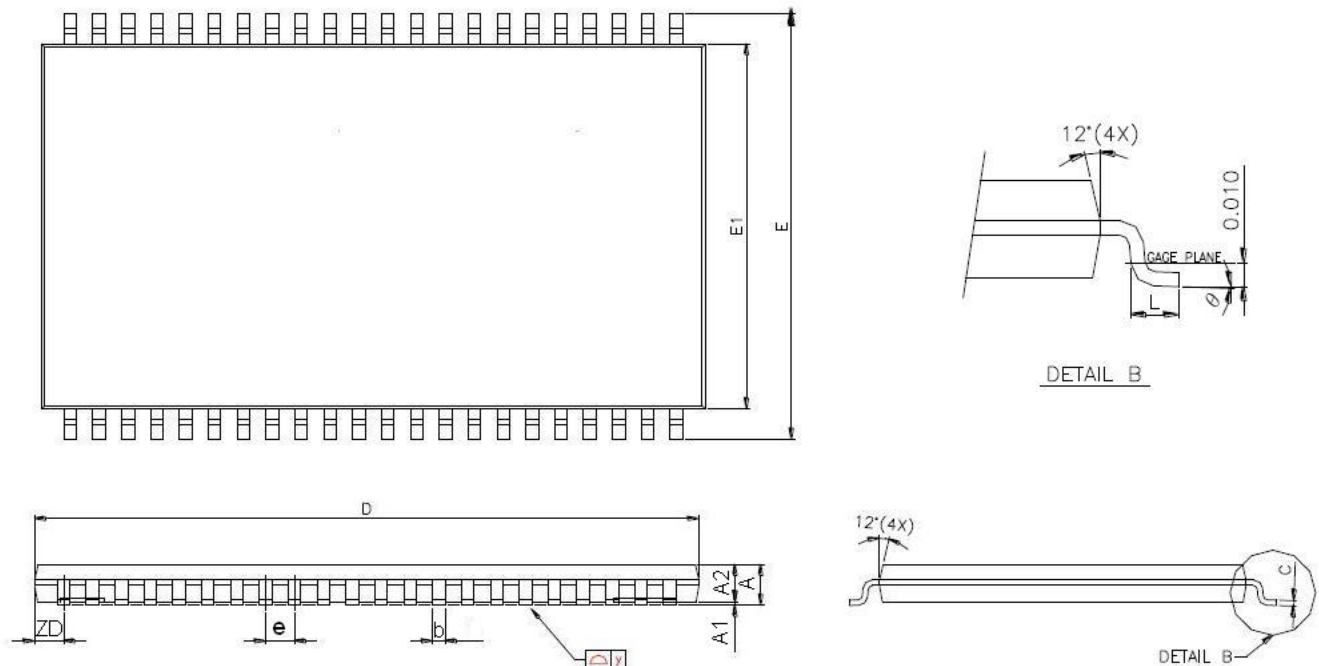
Low V_{CC} Data Retention Waveform (2) (LB#, UB# controlled)





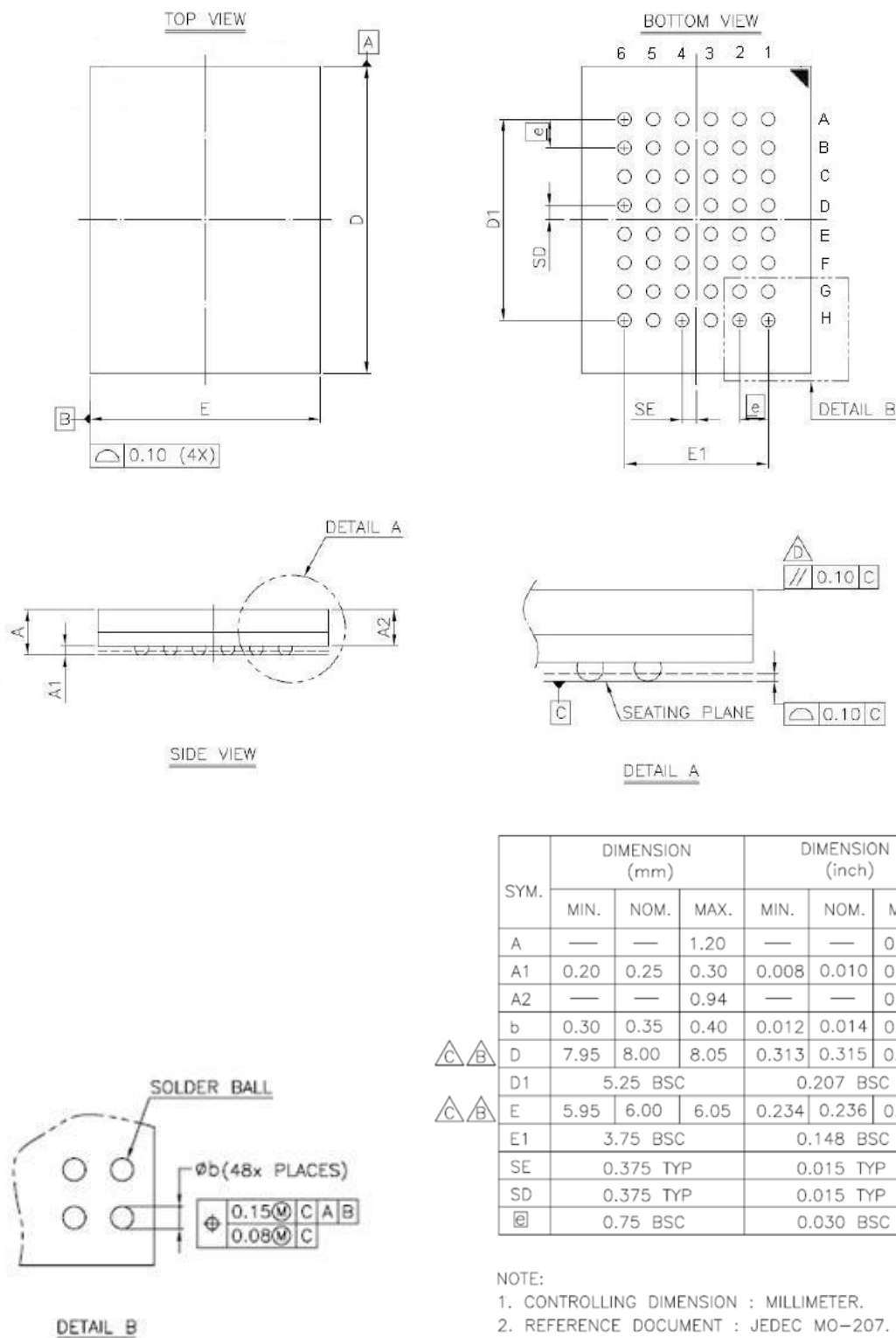
PACKAGE OUTLINE DIMENSION

44-pin 400 mil TSOP II Package Outline Dimension



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN MILS		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	-	-	1.20	-	-	47.2
A1	0.05	0.10	0.15	2.0	3.9	5.9
A2	0.95	1.00	1.05	37.4	39.4	41.3
b	0.30	-	0.45	11.8	-	17.7
c	0.12	-	0.21	4.7	-	8.3
D	18.212	18.415	18.618	717	725	733
E	11.506	11.760	12.014	453	463	473
E1	9.957	10.160	10.363	392	400	408
e	-	0.800	-	-	31.5	-
L	0.40	0.50	0.60	15.7	19.7	23.6
ZD	-	0.805	-	-	31.7	-
y	-	-	0.076	-	-	3
θ	0°	3°	6°	0°	3°	6°

48-ball 6mm × 8mm TFBGA Package Outline Dimension





ORDERING INFORMATION

Package Type	Access Time (Speed)(ns)	Power Type	Temperature Range(°C)	Packing Type	Lyontek Item No.
44-pin (400mil) TSOP II	45	Special Ultra Low Power	0°C~70°C	Tray	LY62W6416BML-45SL
				Tape Reel	LY62W6416BML-45SLT
			-40°C~85°C	Tray	LY62W6416BML-45SLI
				Tape Reel	LY62W6416BML-45SLIT
	55	Special Ultra Low Power	0°C~70°C	Tray	LY62W6416BML-55SL
				Tape Reel	LY62W6416BML-55SLT
			-40°C~85°C	Tray	LY62W6416BML-55SLI
				Tape Reel	LY62W6416BML-55SLIT
	70	Special Ultra Low Power	0°C~70°C	Tray	LY62W6416BML-70SL
				Tape Reel	LY62W6416BML-70SLT
			-40°C~85°C	Tray	LY62W6416BML-70SLI
				Tape Reel	LY62W6416BML-70SLIT



ORDERING INFORMATION

Package Type	Access Time (Speed)(ns)	Power Type	Temperature Range(°C)	Packing Type	Lyontek Item No.
48-ball (6mm x 8mm) TFBGA	45	Special Ultra Low Power	0°C~70°C	Tray	LY62W6416BGL-45SL
				Tape Reel	LY62W6416BGL-45SLT
			-40°C~85°C	Tray	LY62W6416BGL-45SLI
				Tape Reel	LY62W6416BGL-45SLIT
	55	Special Ultra Low Power	0°C~70°C	Tray	LY62W6416BGL-55SL
				Tape Reel	LY62W6416BGL-55SLT
			-40°C~85°C	Tray	LY62W6416BGL-55SLI
				Tape Reel	LY62W6416BGL-55SLIT
	70	Special Ultra Low Power	0°C~70°C	Tray	LY62W6416BGL-70SL
				Tape Reel	LY62W6416BGL-70SLT
			-40°C~85°C	Tray	LY62W6416BGL-70SLI
				Tape Reel	LY62W6416BGL-70SLIT



Lyontek Inc.

LY62W6416B

Rev. 1.1

64K X 16 BIT LOW POWER CMOS SRAM

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